

Features

- $V_{DS} = 30V$
- $R_{DS(ON)} = 1.6m\Omega @ V_{GS}=10 @ I_{DS}=30A$
- $R_{DS(ON)} = 2.1m\Omega @ V_{GS}=4.5 @ I_{DS}=25A$

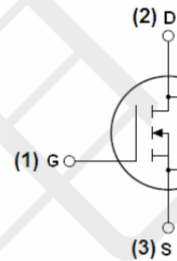
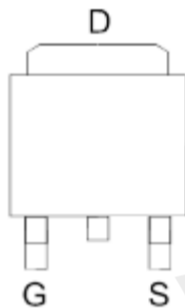
Application

- Simple Drive Requirement
- Small Package Outline
- Surface Mount Device

Package and Pin Configuration

(TO-252-3L)

Top View



Absolute Maximum Ratings ($T_A=25^\circ C$ unless otherwise noted)

Parameter	Symbol	Rating	Units
Drain-Source Voltage	V_{DS}	30	V
Gate-Source Voltage	V_{GS}	± 20	V
Drain Current	I_D	Continuous	150
		Pulsed	340
Total Power Dissipation	P_D	90	W
Operating Junction Temperature Range	T_J	-55 to 150	$^\circ C$

Electrical Characteristics (T_A=25°C unless otherwise noted)

Electrical Characteristics (T _J =25°C unless otherwise noted)						
Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
OFF CHARACTERISTICS (Note 2)						
B _V DSS	Drain-Source Breakdown Voltage	I _D =250μA, V _{GS} =0 V	30			V
I _{DSS}	Drain to Source Leakage Current	V _{DS} = 24V, V _{GS} =0V			1	μA
I _{GSS}	Gate-Body Leakage Current	V _{GS} =20 V			100	nA
V _{GS(th)}	Gate Threshold Voltage	V _{DS} = V _{GS} , I _D =250μA	1	1.7	3.0	V
R _{DS(ON)}	Static Drain-Source On-Resistance ²	V _{GS} =4.5V, I _D =25A	-	2.1		mΩ
		V _{GS} =10V, I _D =30A		1.6	1.9	
DYNAMIC PARAMETERS						
C _{iss}	Input Capacitance	V _{GS} =0V, V _{DS} =15V, f=1MHz		7032		pF
C _{oss}	Output Capacitance			898		pF
C _{rss}	Reverse Transfer Capacitance			743		pF
SWITCHING PARAMETERS						
Q _g	Total Gate Charge ²	V _{GS} =10V, V _{DS} =15V, I _D =30A		80		nC
Q _{gs}	Gate Source Charge			19		nC
Q _{gd}	Gate Drain Charge			38		nC
t _{d(on)}	Turn-On Delay Time	V _{GS} =10V, V _{DS} =15V, R _{GEN} =1Ω I _D =1A		20		ns
t _{d(off)}	Turn-Off Delay Time			80		ns
t _{d(r)}	Turn-On Rise Time			36		ns
t _{d(f)}	Turn-Off Fall Time			33		ns
Thermal Resistance						
Symbol	Parameter		Typ	Max		Units
R _{θJC}	Junction to Case		-	2		°C/W
R _{θJA}	Junction to Ambient (t ≤ 10s)		-	50		°C/W

Typical Characteristics

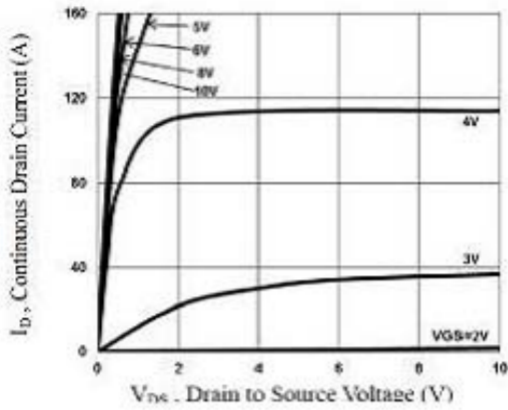


Figure 1: Typical Output Characteristics

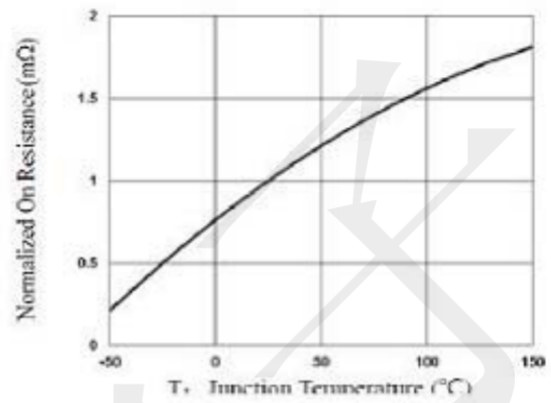


Figure 2: Normalized $R_{DS(on)}$ vs. T_J

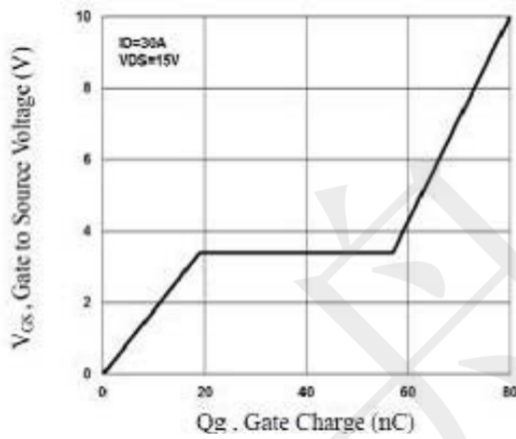


Figure 3: Gate-Charge Characteristics

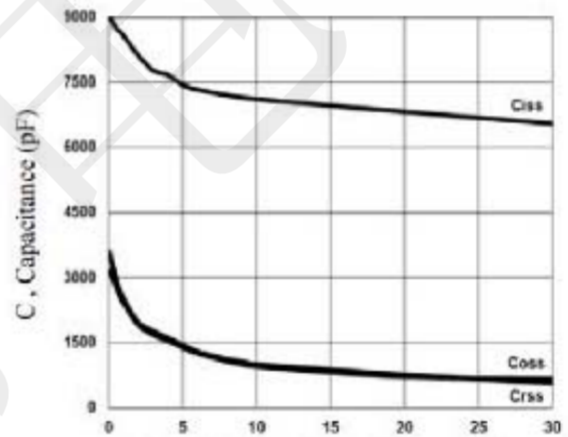


Figure 4: Capacitance Characteristics

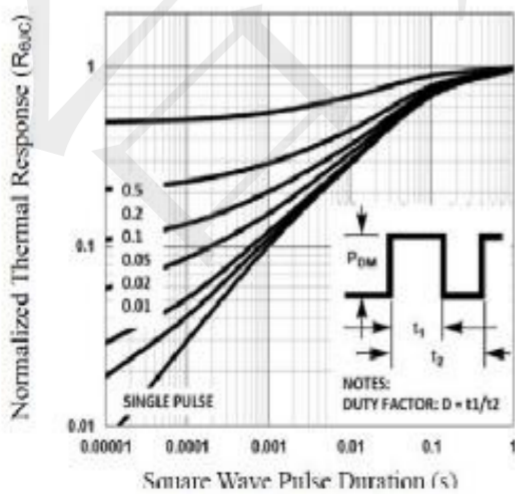


Figure 5: Normalized Thermal transient Impedance Curve

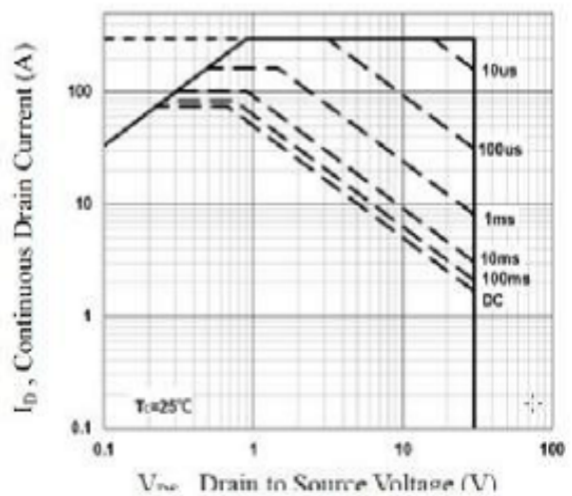
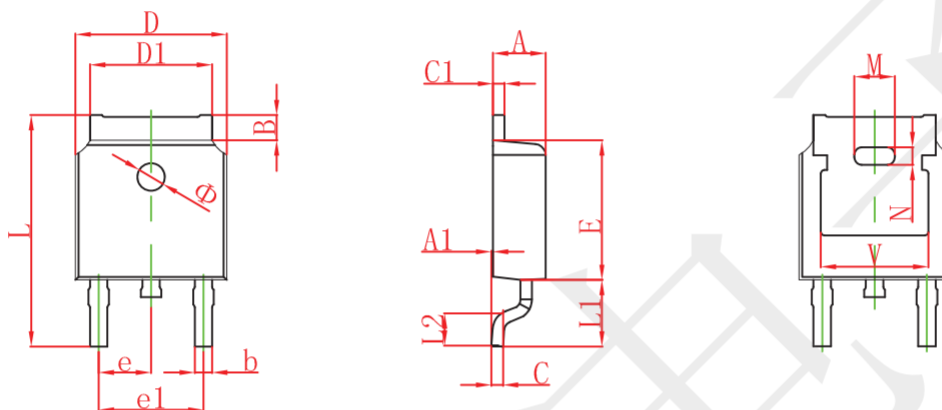


Figure 6: Maximum Safe Operation Area

TO252 Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	2.200	2.380	0.087	0.094
A1	0.000	0.100	0.000	0.004
B	0.800	1.400	0.031	0.055
b	0.710	0.810	0.028	0.032
c	0.460	0.560	0.018	0.022
c1	0.460	0.560	0.018	0.022
D	6.500	6.700	0.256	0.264
D1	5.130	5.460	0.202	0.215
E	6.000	6.200	0.236	0.244
e	2.286 TYP.		0.090 TYP.	
e1	4.327	4.727	0.170	0.186
M	1.778REF.		0.070REF.	
N	0.762REF.		0.018REF.	
L	9.800	10.400	0.386	0.409
L1	2.9REF.		0.114REF.	
L2	1.400	1.700	0.055	0.067
V	4.830 REF.		0.190 REF.	
Φ	1.100	1.300	0.043	0.051